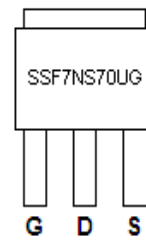
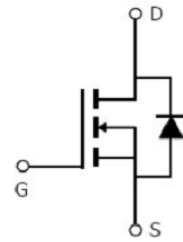


Main Product Characteristics:

V_{DSS}	700V
$R_{DS(on)}$	0.7 Ω (typ.)
I_D	7A ^①


TO-251 (IPAK)

Marking and Pin Assignment

Schematic Diagram
Features and Benefits:

- High dv/dt and avalanche capabilities
- 100% avalanche tested
- Low input capacitance and gate charge
- Low gate input resistance


Description:

The SSF7NS70UG series MOSFETs is a new technology, which combines an innovative technology and advance process. This new technology achieves low Rdson, energy saving, high reliability and uniformity, superior power density and space saving.

Absolute Max Rating:

Symbol	Parameter	Max.	Units
I_D @ TC = 25°C	Continuous Drain Current, V_{GS} @ 10V	7 ^①	A
I_D @ TC = 100°C	Continuous Drain Current, V_{GS} @ 10V	4.3 ^①	
I_{DM}	Pulsed Drain Current ^②	21	
P_D @TC = 25°C	Power Dissipation ^③	41	W
	Linear Derating Factor	0.33	W/°C
V_{DS}	Drain-Source Voltage	700	V
V_{GS}	Gate-to-Source Voltage	± 30	V
E_{AS}	Single Pulse Avalanche Energy @ L=100mH	112	mJ
I_{AS}	Avalanche Current @ L=100mH	1.5	A
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to +150	°C

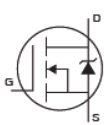
Thermal Resistance

Symbol	Characteristics	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-case ③	—	3.0	$^{\circ}\text{C}/\text{W}$
$R_{\theta JA}$	Junction-to-ambient ($t \leq 10\text{s}$) ④	—	62	$^{\circ}\text{C}/\text{W}$

Electrical Characteristics @ $T_A=25^{\circ}\text{C}$ unless otherwise specified

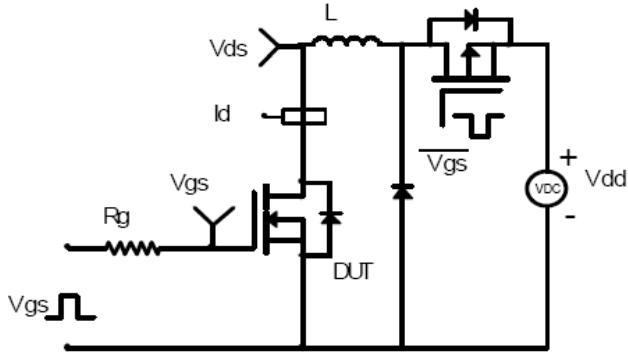
Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source breakdown voltage	700	—	—	V	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$
$R_{DS(on)}$	Static Drain-to-Source on-resistance	—	0.7	0.85	Ω	$V_{GS}=10\text{V}, I_D = 1\text{A}$
		—	1.5	—		$T_J = 125^{\circ}\text{C}$
		—	0.85	0.95	Ω	$V_{GS}=10\text{V}, I_D = 4.8\text{A}$
		—	2.3	—		$T_J = 125^{\circ}\text{C}$
$V_{GS(th)}$	Gate threshold voltage	3	—	5	V	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$
		—	3.3	—		$T_J = 125^{\circ}\text{C}$
I_{DSS}	Drain-to-Source leakage current	—	—	1	μA	$V_{DS} = 700\text{V}, V_{GS} = 0\text{V}$
		—	—	50		$T_J = 125^{\circ}\text{C}$
I_{GSS}	Gate-to-Source forward leakage	—	—	100	nA	$V_{GS} = 30\text{V}$
		—	—	-100		$V_{GS} = -30\text{V}$
Q_g	Total gate charge	—	12	—	nC	$I_D = 2.2\text{A},$ $V_{DS}=480\text{V},$ $V_{GS} = 10\text{V}$
Q_{gs}	Gate-to-Source charge	—	3.2	—		
Q_{gd}	Gate-to-Drain("Miller") charge	—	5.2	—		
$t_{d(on)}$	Turn-on delay time	—	12	—	ns	$V_{GS}=10\text{V}, V_{DS} = 400\text{V},$ $R_{GEN}=10.2\Omega, I_D = 2.2\text{A}$
t_r	Rise time	—	8.6	—		
$t_{d(off)}$	Turn-Off delay time	—	24	—		
t_f	Fall time	—	14	—		
C_{iss}	Input capacitance	—	525	—	pF	$V_{GS} = 0\text{V}$
C_{oss}	Output capacitance	—	21	—		$V_{DS} = 100\text{V}$
C_{rss}	Reverse transfer capacitance	—	2.7	—		$f = 1\text{MHz}$

Source-Drain Ratings and Characteristics

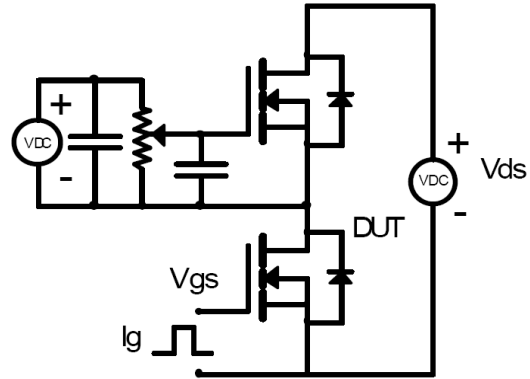
Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	7 ①	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I_{SM}	Pulsed Source Current (Body Diode)	—	—	21	A	
V_{SD}	Diode Forward Voltage	—	0.85	1.2	V	$I_S=4.8\text{A}, V_{GS}=0\text{V}$
t_{rr}	Reverse Recovery Time	—	132	—	nS	$T_J = 25^{\circ}\text{C}, I_F = 2.2\text{A},$ $di/dt = 100\text{A}/\mu\text{s}$
Q_{rr}	Reverse Recovery Charge	—	805	—	nC	

Test circuits and Waveforms

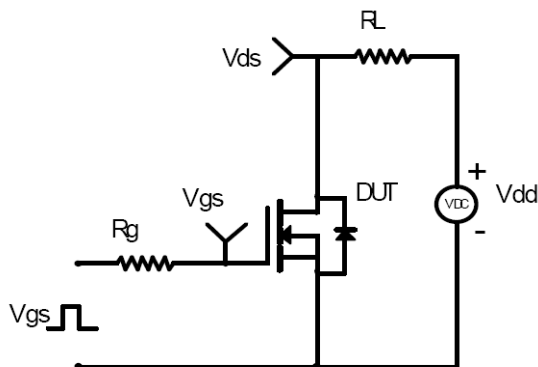
EAS Test Circuit:



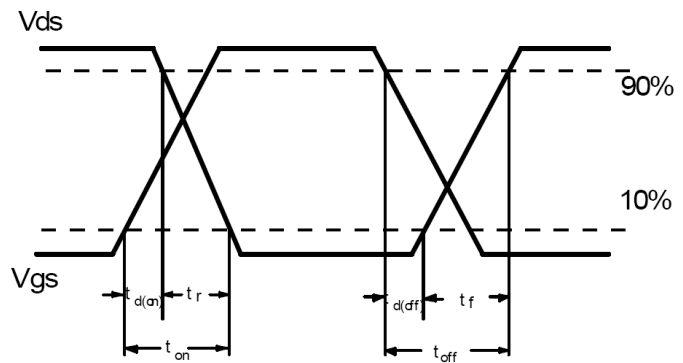
Gate charge test circuit:



Switching Time Test Circuit:



Switching Waveforms:



Notes:

- ① Calculated continuous current based on maximum allowable junction temperature.
- ② Repetitive rating; pulse width limited by max. junction temperature.
- ③ The power dissipation PD is based on max. junction temperature, using junction-to-case thermal resistance.
- ④ The value of $R_{\theta JA}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$

Typical electrical and thermal characteristics

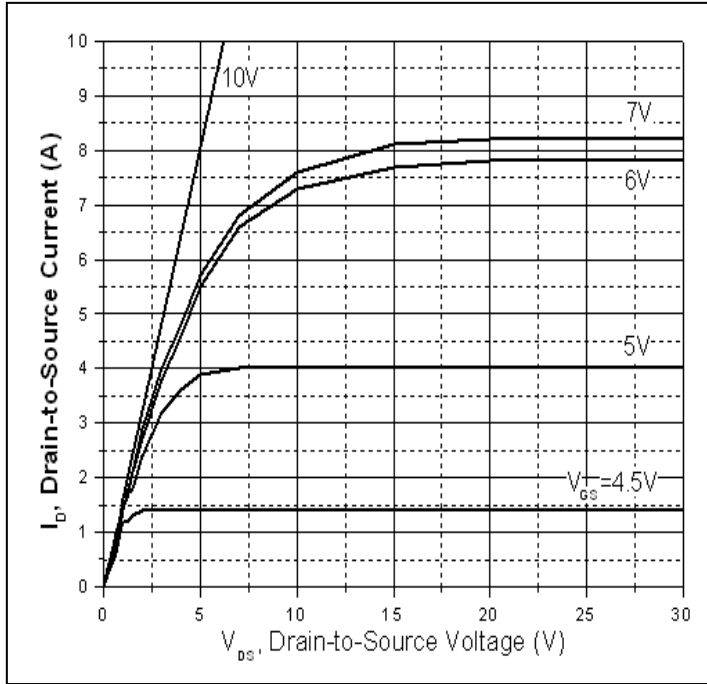


Figure 1: Typical Output Characteristics

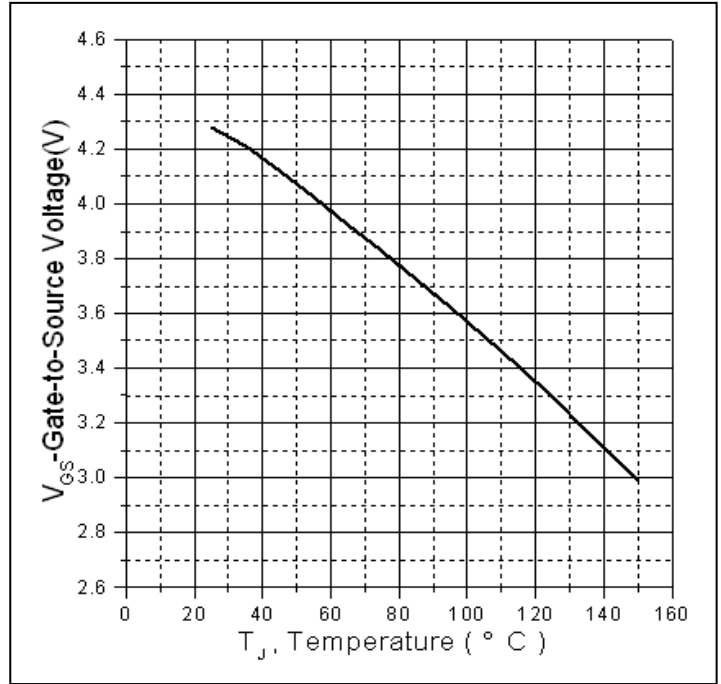


Figure 2. Gate to source cut-off voltage

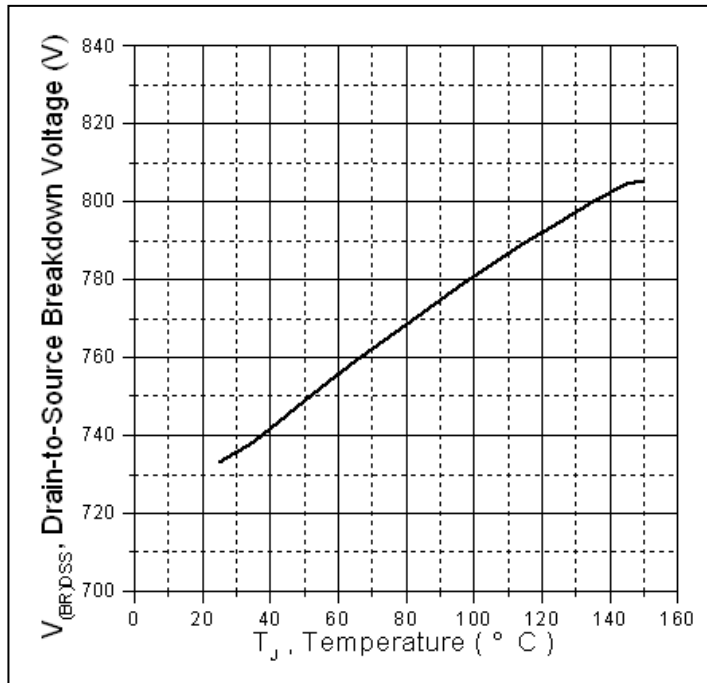


Figure 3. Drain-to-Source Breakdown Voltage Vs. Case Temperature

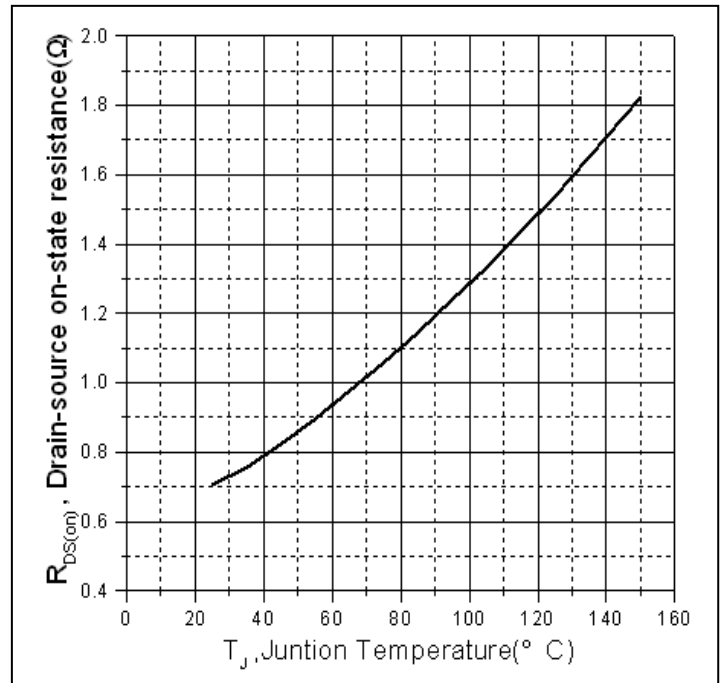


Figure 4: Normalized On-Resistance Vs. Case Temperature ($V_{GS}=10V, I_D = 1A$)

Typical electrical and thermal characteristics

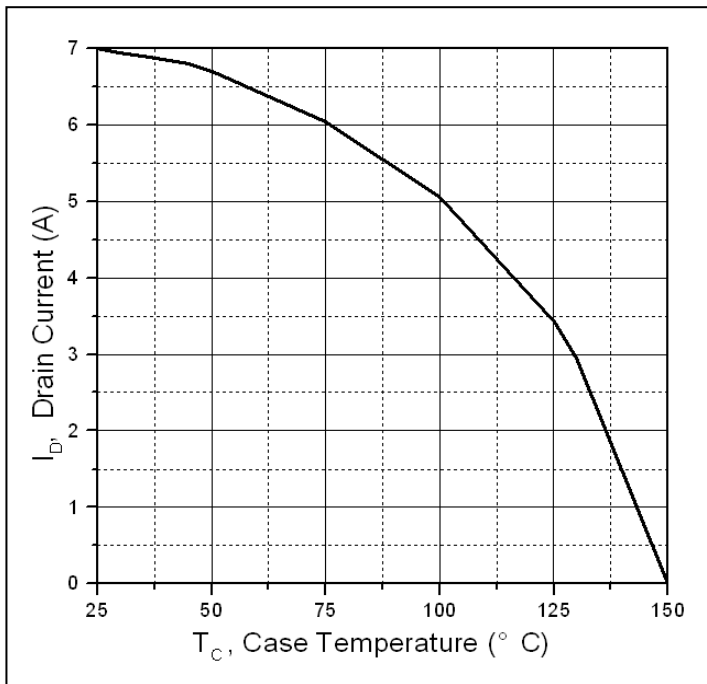


Figure 5. Maximum Drain Current Vs. Case Temperature

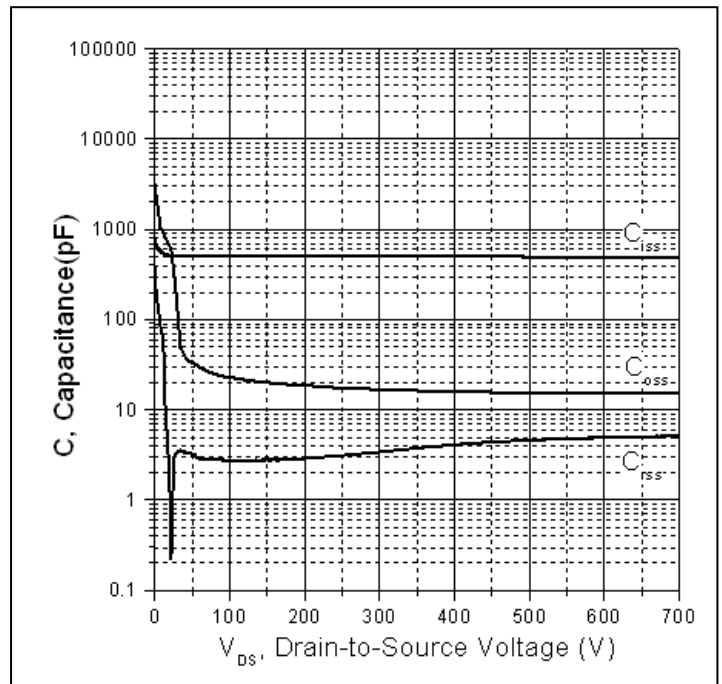


Figure 6. Typical Capacitance Vs. Drain-to-Source Voltage

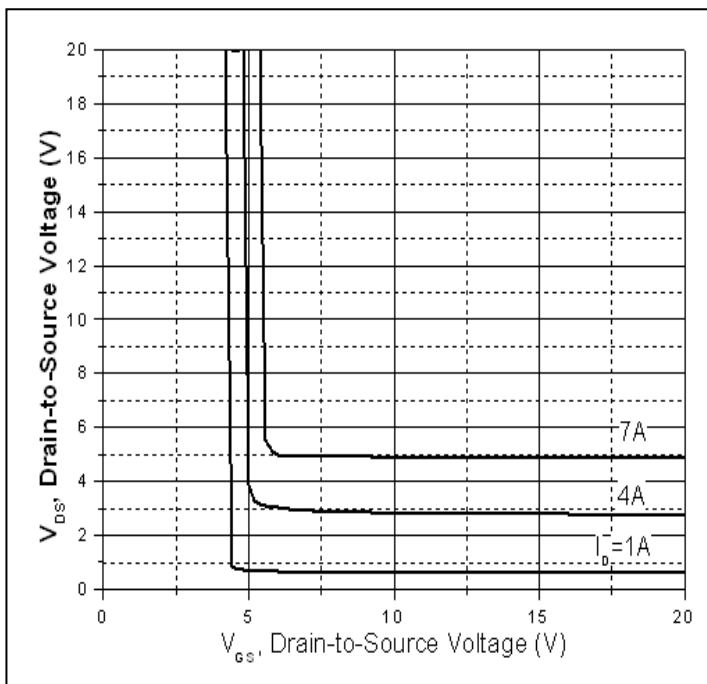


Figure7. Drain-to-Source Voltage Vs. Gate-to-Source Voltage

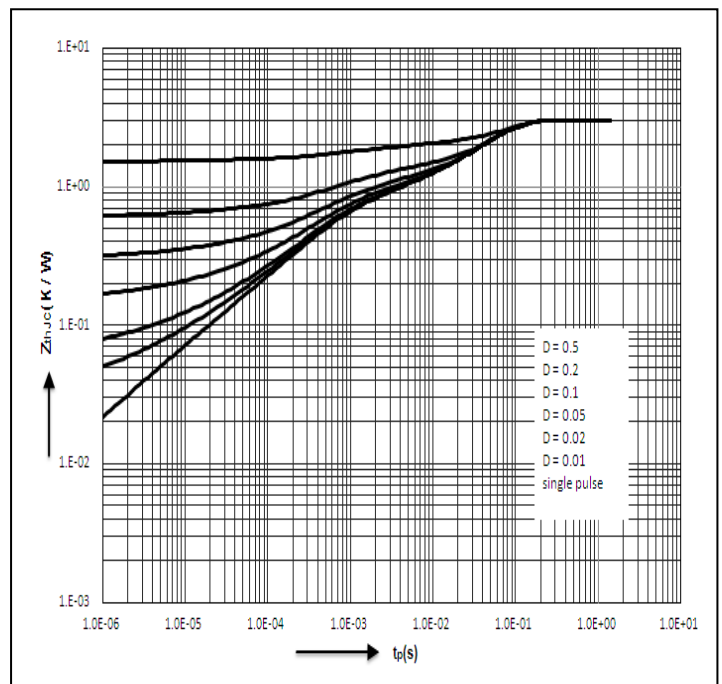
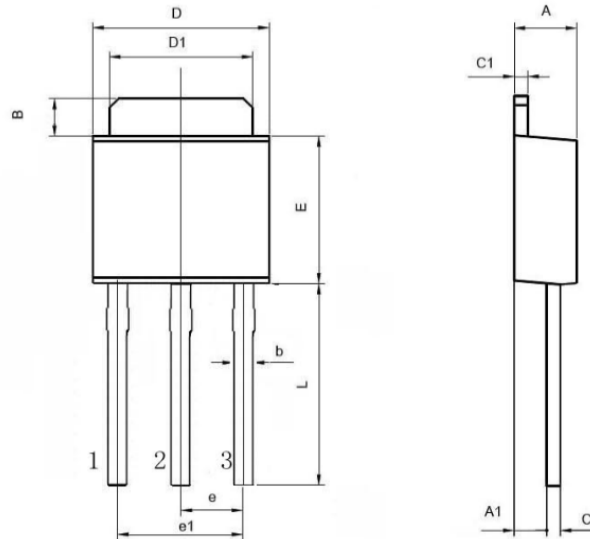


Figure8. Maximum Effective Transient Thermal Impedance, Junction-to-Case

Mechanical Data:
TO-251 PACKAGE OUTLINE DIMENSION


Symbol	Dimension In Millimeters			Dimension In Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.200	-	2.400	0.087	-	0.094
A1	0.950	-	1.150	0.037	-	0.045
B	0.950	-	1.250	0.037	-	0.049
b	0.500	-	0.700	0.020	-	0.028
c	0.450	-	0.550	0.018	-	0.022
c1	0.450	-	0.550	0.018	-	0.022
D	6.450	-	6.750	0.254	-	0.266
D1	5.200	-	5.400	0.205	-	0.213
E	5.950	-	6.250	0.234	-	0.246
e	2.240	-	2.340	0.088	-	0.092
e1	4.430	-	4.730	0.174	-	0.186
L	9.000	-	9.400	0.354	-	0.370

Ordering and Marking Information**Device Marking: SSF7NS70UG**

Package (Available)
TO-251(IPAK)
Operating Temperature Range
C : -55 to 150 °C

Devices per Unit

Package Type	Units/ Tube	Tubes/Inner Box	Units/Inner Box	Inner Boxes/Carton Box	Units/Carton Box
TO-251	75	48	3600	5	18000

Reliability Test Program

Test Item	Conditions	Duration	Sample Size
High Temperature Reverse Bias(HTRB)	$T_j=150^{\circ}\text{C}$ @ 80% of Max $V_{DSS}/V_{CES}/V_R$	168 hours 500 hours 1000 hours	3 lots x 77 devices
High Temperature Gate Bias(HTGB)	$T_j=150^{\circ}\text{C}$ @ 100% of Max V_{GSS}	168 hours 500 hours 1000 hours	3 lots x 77 devices

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